

GST2035B08TIF

20A TRIAC

Product Description

It is a Triac with V_{RRM} 800V and $I_{T(RMS)}$ 20A.

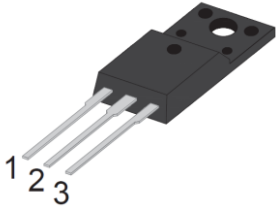
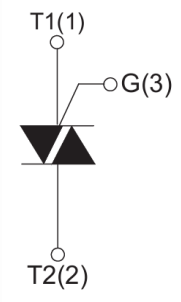
Features

- Glass Passivated Chip Junction
- High Voltage and Surge Capability
- Triggering in Three Quadrants

Mechanical Data

- TO-220F Package
- RoHS Compliant and Halogen Free

Packages & Pin Assignments

TO-220F			Equivalent Circuit
			
Pin	Symbol	Description	
1	T1	Terminal 1	
2	T2	Terminal 2	
3	G	Gate	

Ordering and Marking Information

Ordering Information				
Part Number	Package	Marking	Quantity	Packaging Type
GST2035B08TIF	TO-220F	<div> <div>□□□</div> T2035-800TF </div>	50 PCS	Tube
GST2035B 1 1 2 2 F <div> <div>- Product Code: GST2035B</div> <div>- Voltage Code: 1 1 is 08 for 800 V_{RRM}</div> <div>- Package Code: 2 2 TI for TO-220F</div> </div> <div> <div>- Green Level: F for RoHS Compliant and Halogen Free</div> </div>				
Marking Information				
<div> <div>□□□</div> T2035-800TF </div>		- Product Code: T2035-800TF	- GS Code: □□□	

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DRM}	Repetitive peak off-state voltage (T _J = 25°C)	800	V
V _{RRM}	Repetitive peak reverse voltage (T _J = 25°C)	800	V
I _{T(RMS)}	RMS on-state current (T _C =75°C)	20	A
I _{TSM}	Non repetitive surge peak on-state current (180° conduction angle, f = 50Hz, t _P = 20ms, full cycle)	200	A
I ² t	Value for fusing (t _P = 10ms)	200	A ² S
dI/dt	Critical rate of rise of on-state current (I _G = 2×I _{GT} , t _r ≤ 100ns)	100	A/μs
I _{GM}	Peak gate current	4	A
P _{G(AV)}	Average gate power dissipation	1	W
R _{ΘJC}	Thermal Resistance, Junction to Case	2.1	°C/W
T _J	Junction Temperature Range	-40 to +150	°C
T _{STG}	Storage Temperature Range	-40 to +150	°C

Electrical Characteristics (T_A=25°C unless otherwise specified)

Logic Level & Snubberless (3 Quadrants)

Symbol	Test Condition	Quadrant	Min	Max	Unit
I _{GT}	V _D = 12V, R _L = 100Ω	I - II - III	-	35	mA
V _{GT}	V _D = 12V, R _L = 100Ω	I - II - III	-	1.3	V
V _{GD}	V _D = V _{DRM} , T _J = 125°C	I - II - III	0.2	-	V
I _L	I _G = 1.2×I _{GT}	I - III	-	50	mA
		II		90	
I _H	V _{AK} = 12V, I _{GK} = 100mA		-	40	mA
dV/dt	V _D = 67% V _{DRM} , Gate Open	T _J = 125°C	500	-	V/μs
V _{TM}	I _{TM} = 28A, t _P = 380μs	T _J = 25°C	-	1.5	V
I _{DRM/RRM}	V _D = V _{DRM} , V _R = V _{RRM}	T _J = 25°C	-	5	μA
		T _J = 125°C	-	2.5	mA

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

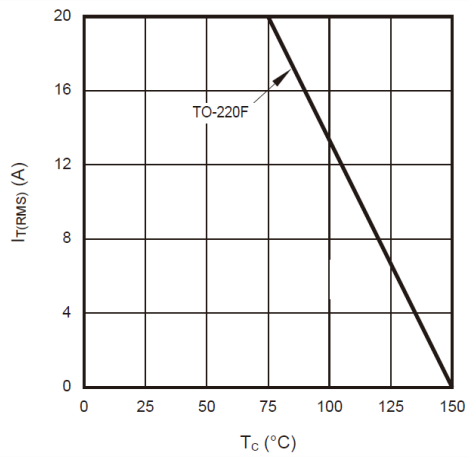


Figure 1. $I_{T(RMS)}$ vs. T_c

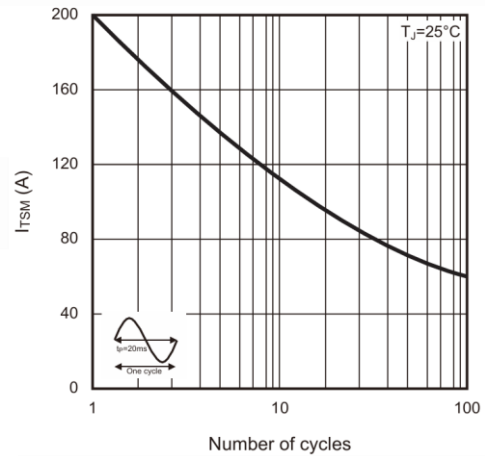


Figure 2. I_{TSM} vs. Number of Cycle

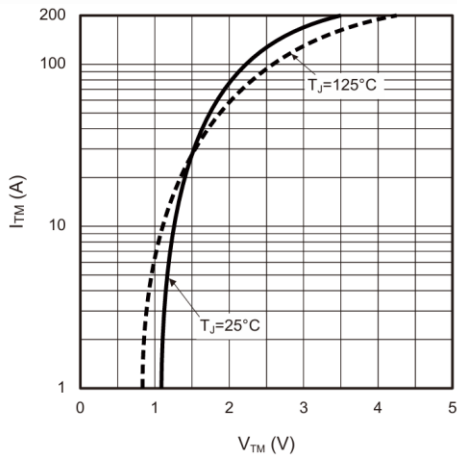


Figure 3. ON State Characteristics

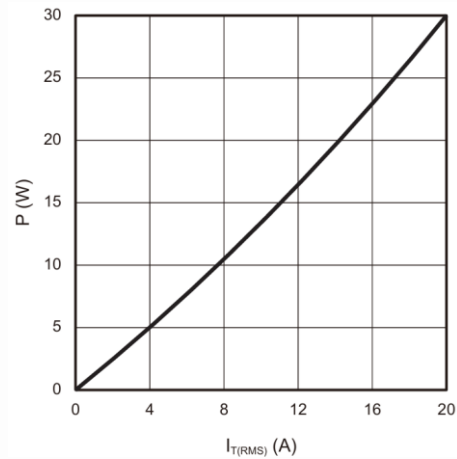


Figure 4. P_D vs. $I_{T(RMS)}$

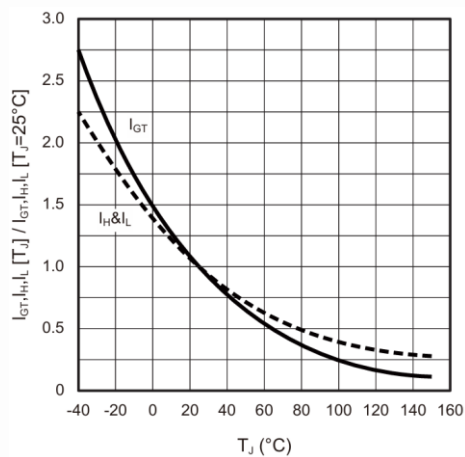
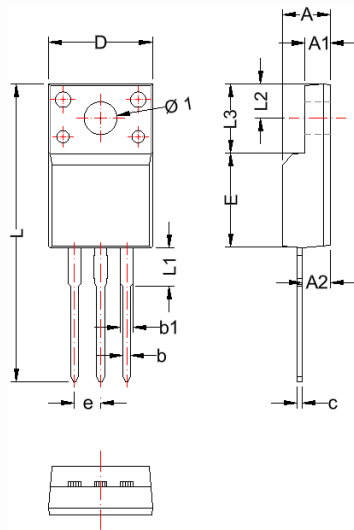


Figure 5. Relative Variations of I_G , I_H and I_L vs. T_J

TO-220F

Package Dimension



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	4.00	5.10	0.157	0.201
A1	2.34	3.30	0.092	0.130
A2	2.10	3.20	0.083	0.126
b	0.30	0.90	0.012	0.035
b1	0.90	1.70	0.035	0.067
C	0.40	0.80	0.016	0.031
D	9.50	10.70	0.374	0.421
E	8.30	9.30	0.327	0.366
e	2.54 BSC		0.100 BSC	
L	28.00	29.80	1.102	1.173
L1	2.50	4.30	0.098	0.169
L2	2.50	3.60	0.098	0.142
L3	6.30	7.50	0.248	0.295
Ø1	2.70	4.31	0.106	0.170





NOTE:



Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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